

Electronic Patent Application Fee Transmittal

| Application Number: | 10773434 | | | |
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| Filing Date: | 09-Feb-2004 | | | |
| Title of Invention: | ELECTROPLATED INTERCONNECTION STRUCTURES ON INTEGRATED CIRCUIT CHIPS | | | |
| First Named Inventor/Applicant Name: | Panayotis Constantinou Andricacos | | | |
| Filer: | Wenjie Li/Carol Riedinger | | | |
| Attorney Docket Number: | YOR91995137X | | | |
| Filed as Large Entity | | | | |
| Utility under 35 USC 111(a) Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Certificate of correction | 1811 | 1 | 100 | 100 |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 100 |